

COPPER-NICKEL ALLOY ELECTROPLATING BATH AND PLATING METHOD

Abstract

The present invention provides a copper-nickel alloy
5 electroplating bath which is characterized by containing (a)
a copper salt and a nickel salt, (b) a metal complexing agent,
(c) a plurality of conductivity-imparting salts that are
different from each other, (d) a compound that is selected from
the group consisting of disulfide compounds, sulfur-containing
10 amino acids and salts of these compounds, (e) a compound that
is selected from the group consisting of sulfonic acid compounds,
sulfimide compounds, sulfamic acid compounds, sulfone amides
and salts of these compounds, and (f) a reaction product of a
glycidyl ether and a polyhydric alcohol. This copper-nickel
15 alloy electroplating bath is also characterized by having a pH
of 3-8.

No Suitable Figure